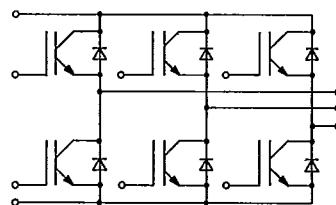
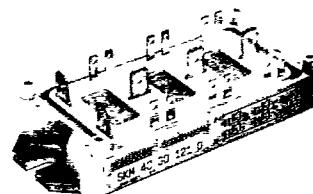


T-39-31



Absolute Maximum Ratings

Symbol	Conditions ¹⁾	Values		
		... 101 D	... 121 D	Units
V _{CES}		1000	1200	V
V _{CGR}	R _{GE} = 20 kΩ	1000	1200	V
I _C	T _{case} = 25/80 °C	40/25		A
I _{CM}	T _{case} = 25/80 °C	80/50		A
V _{GES}		± 20		V
P _{tot}	per IGBT, T _{case} = 25 °C	300		W
T _j , T _{stg}		- 55 ... +150		°C
V _{isol}	AC, 1 min	2 500		V
humidity	DIN 40 040	Class F		
climate	DIN IEC 68 T.1	55/150/56		
Inverse Diode				
I _F = - I _C		40		A
I _{FM} = - I _{CM}		80		A

Characteristics

Symbol	Conditions ¹⁾	min.	typ.	max.	Units
V _{(BR)CES}	V _{GE} = 0, I _C = 0,75 mA	≥ V _{CES}	-	-	V
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 2 mA	4,5	5,5	6,5	V
I _{CES}	{ V _{GE} = 0 T _j = 25 °C	-	-	0,75	mA
I _{GES}	V _{CE} = V _{CES} T _j = 125 °C	-	-	3	mA
V _{CESat}	V _{GE} = 20 V, V _{CE} = 0	-	-	100	nA
g _{fs}	{ V _{GE} = 15 V T _j = 25 °C	-	3,4	3,8	V
	I _C = 40 A T _j = 150 °C	-	4,6	5	V
	V _{CE} = 20 V, I _C = 40 A	11	17	-	S
C _{CHC}	per IGBT	-	-	60	pF
C _{ies}	{ V _{GE} = 0	-	4	-	nF
C _{oes}	V _{CE} = 25 V	-	320	-	pF
C _{res}	f = 1 MHz	-	130	-	pF
L _{CE}		-	-	20	nH
t _{d(on)}	{ V _{CC} = 600 V	--	50 ³⁾	-	ns
t _r	I _C = 40 A ³⁾	-	110 ³⁾	-	ns
t _{d(off)}	{ V _{GE} = 15 V	-	200 ^{3)/200} ⁴⁾	-	ns
t _r	R _{Gon} = R _{Goff} = 47 Ω	-	500 ^{3)/100} ⁴⁾	-	ns
W _{off12} ⁵⁾	T _j = 125 °C	-	2,4 ⁴⁾	-	mWs
W _{off23} ⁵⁾		-	1,2 ⁴⁾	-	mWs

Inverse Diode SKM 40 GD 101 D

V _F = V _{EC}	I _F = 40 A, V _{GE} = 0; (T _j =125 °C)	-	2,2 (1,8)	2,6	V
t _{rr}	T _j = 25 °C ²⁾	-	70	-	ns
	T _j = 125 °C ²⁾	-	150	-	ns
Q _{rr}	T _j = 25/125 °C ²⁾	-	1,3/5	-	μC
f _s	f _s = t _f / (t _{rr} - t _f)	-	1 ²⁾	-	

Inverse Diode SKM 40 GD 121 D

V _F = V _{EC}	I _F = 40 A, V _{GE} = 0; (T _j =125 °C)	-	2,5 (1,9)	3	V
t _{rr}	T _j = 25 °C ²⁾	-	-	-	ns
	T _j = 125 °C ²⁾	-	170	-	ns
Q _{rr}	T _j = 25/125 °C ²⁾	-	1,5/6	-	μC
f _s	f _s = t _f / (t _{rr} - t _f)	-	1 ²⁾	-	

Thermal Characteristics

R _{thjc}	per IGBT	-	-	0,4	°C/W
R _{thjc}	per diode	-	-	1,0	°C/W
R _{thch}	per module	-	-	0,05	°C/W

Cases and mechanical data see page B 6 – 94

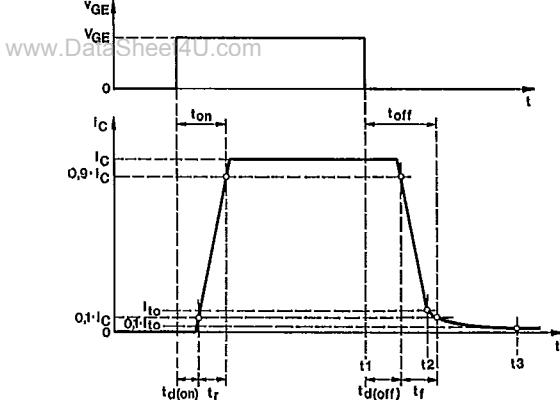
¹⁾ T_{case} = 25 °C, unless otherwise specified

²⁾ I_F = - I_C, V_R = 600 V, - di_F/dt = 800 A/μs, V_{GE} = 0

³⁾ resistive load

⁴⁾ inductive load

⁵⁾ see fig. 21; R_{Goff} = 9,5 Ω



$$W_{off\ 12} = \int_{t_1}^{t_2} i_C \cdot V_{CE} \cdot dt$$

$$W_{off\ 23} = \int_{t_2}^{t_3} i_C \cdot V_{CE} \cdot dt$$

Fig. 21 Switching times and turn-off energies

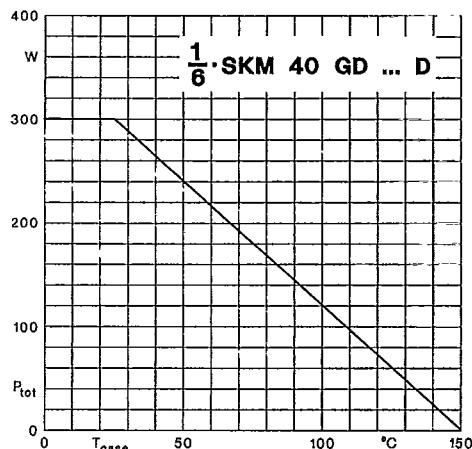


Fig. 22 Rated power dissipation vs. temperature

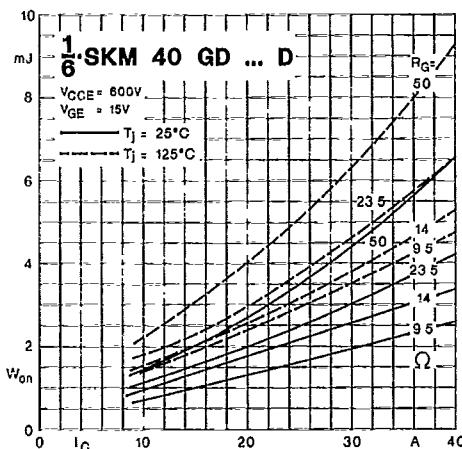


Fig. 23 Turn-on energy dissipation per pulse

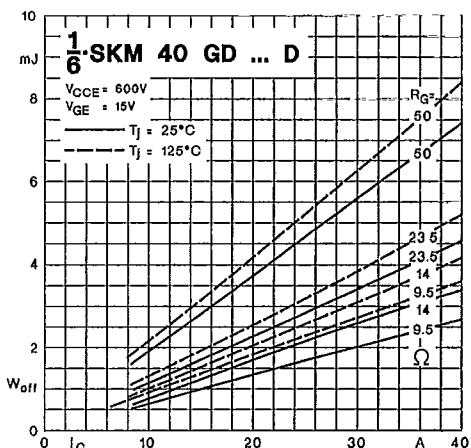


Fig. 24 Turn-off energy dissipation per pulse

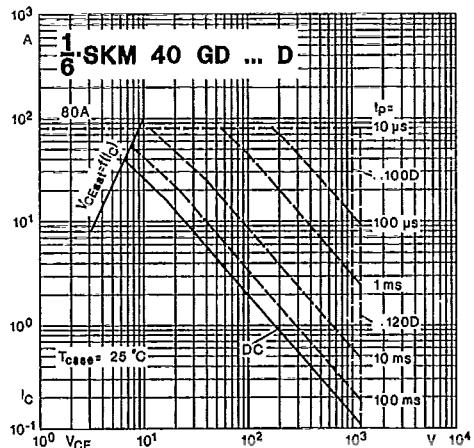


Fig. 25 Maximum safe operating area

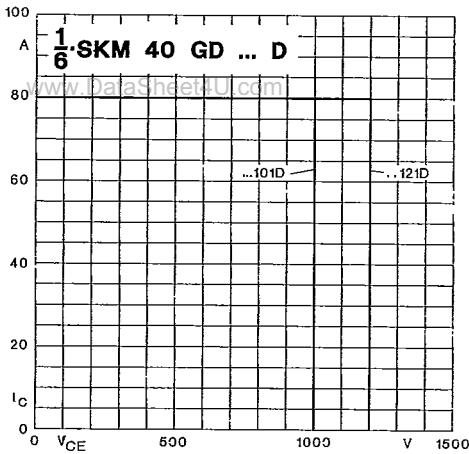


Fig. 26 Turn-off safe operating area

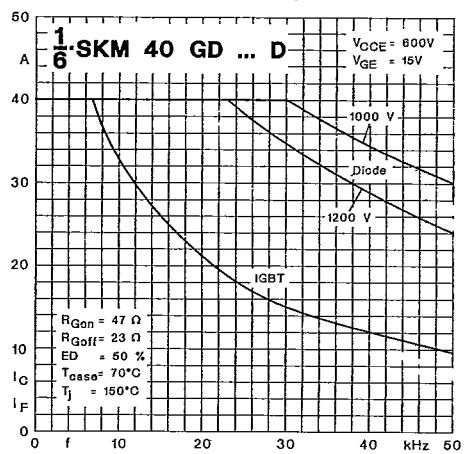


Fig. 27 Rated current vs. pulse frequency

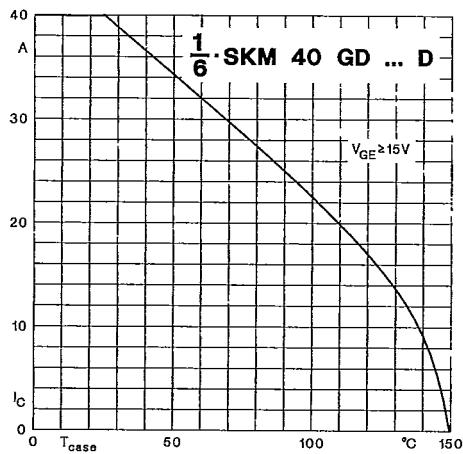


Fig. 28 Rated current vs. temperature

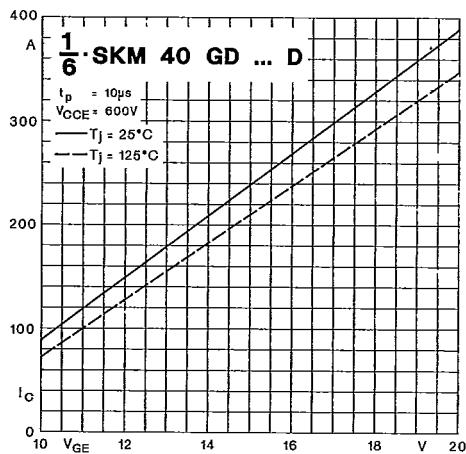


Fig. 29 Short-circuit current vs. turn-on gate voltage

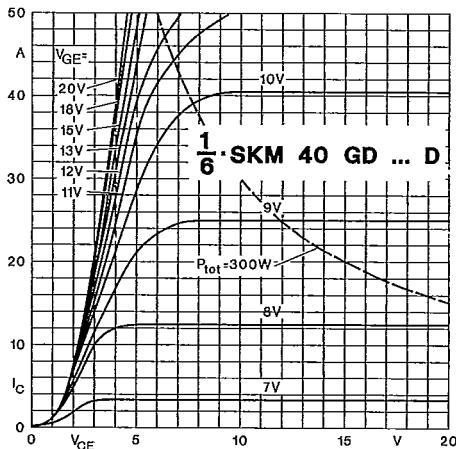


Fig. 30 Output characteristic

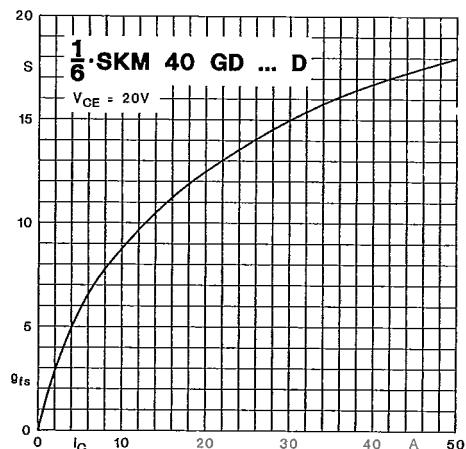
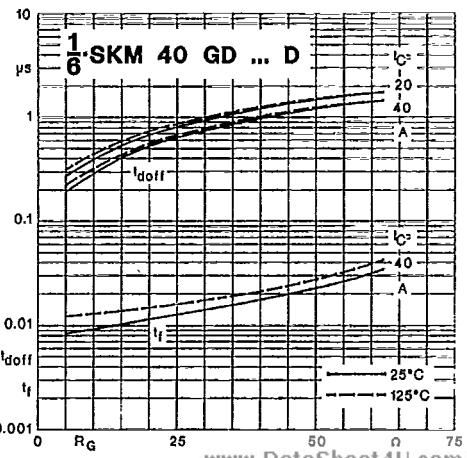
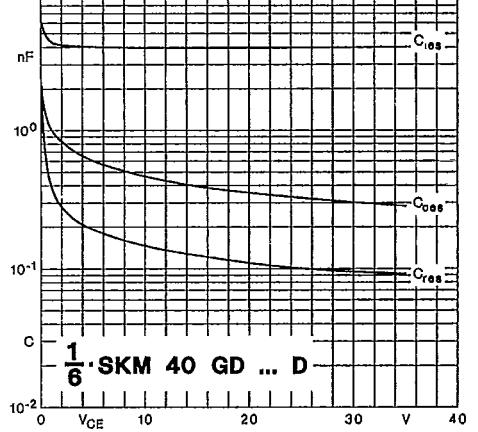
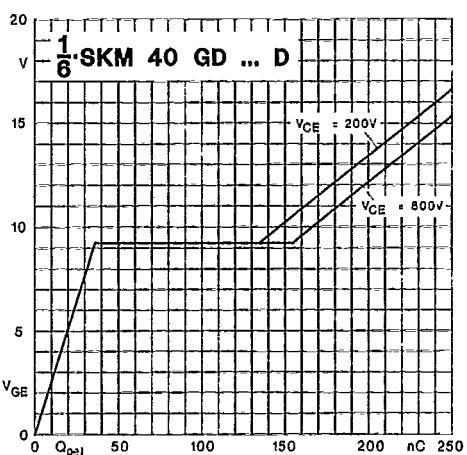
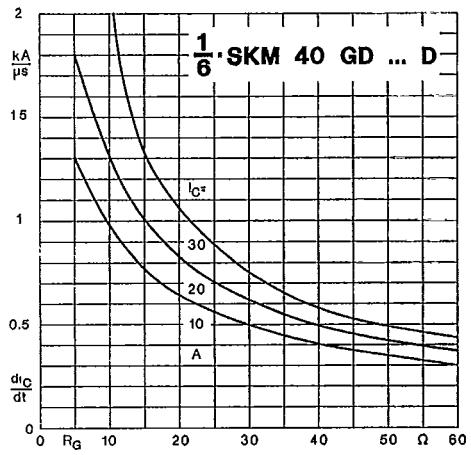
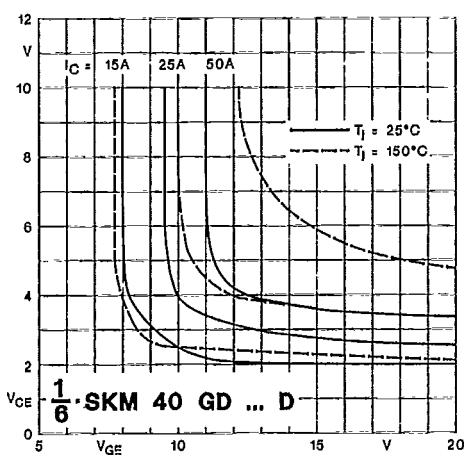
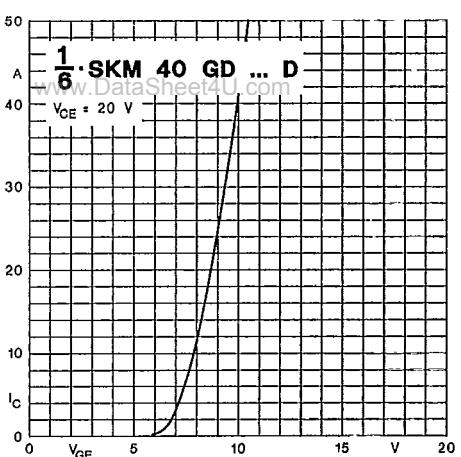


Fig. 31 Forward transconductance



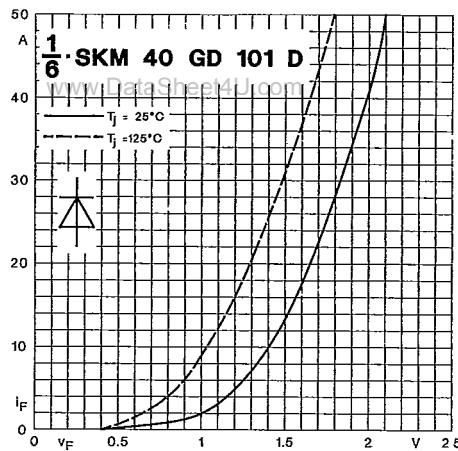


Fig. 38 a Diode forward characteristic

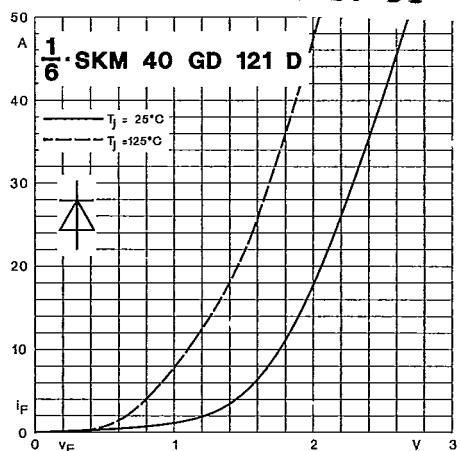


Fig. 38 b Diode forward characteristic

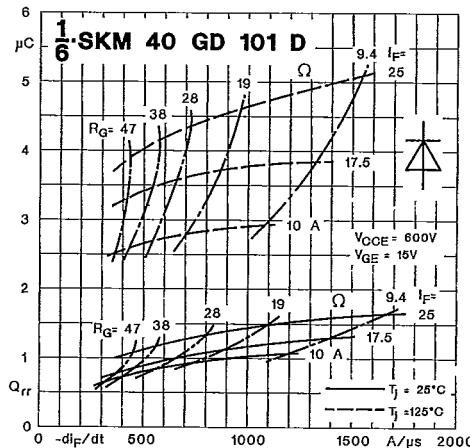


Fig. 39 a Diode recovered charge

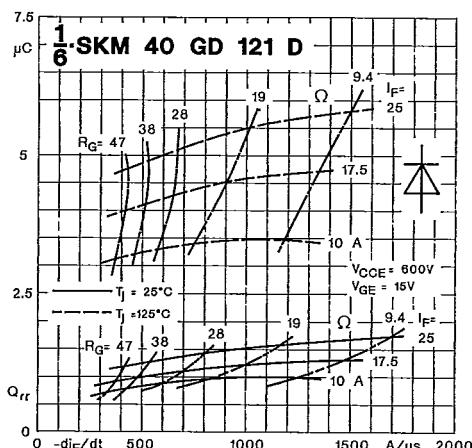


Fig. 39 b Diode recovered charge

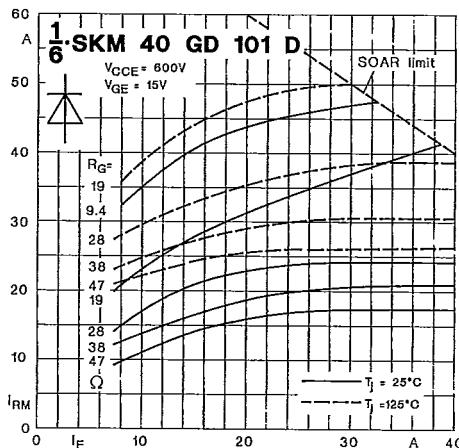


Fig. 40 a Diode peak reverse recovery current (I_{RM})

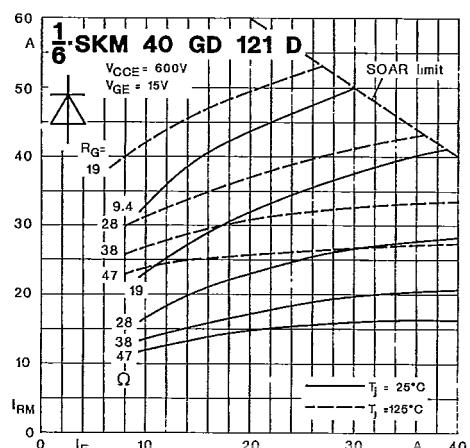


Fig. 40 b Diode peak reverse recovery current (I_{RM})

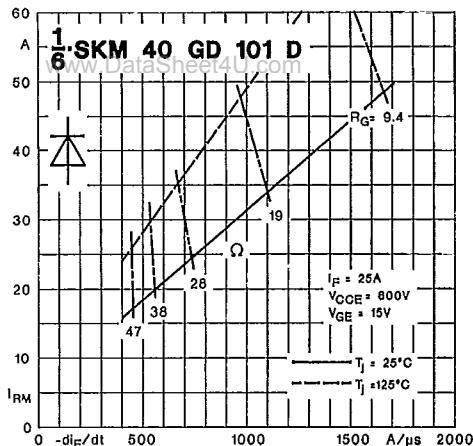


Fig. 41 a Diode peak reverse recovery current ($-di_F/dt$)

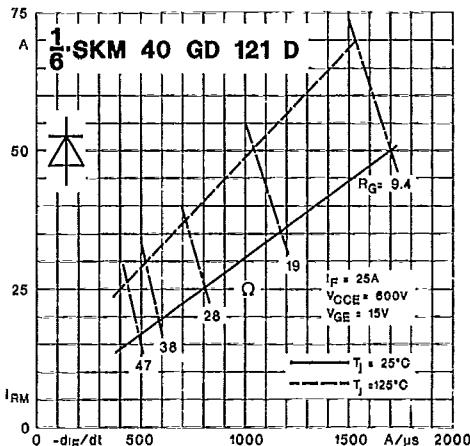


Fig. 41 b Diode peak reverse recovery current ($-di_F/dt$)

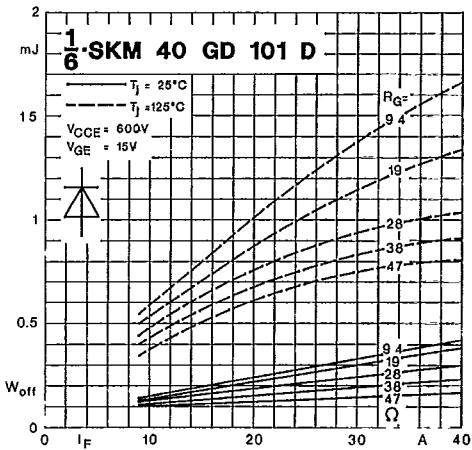
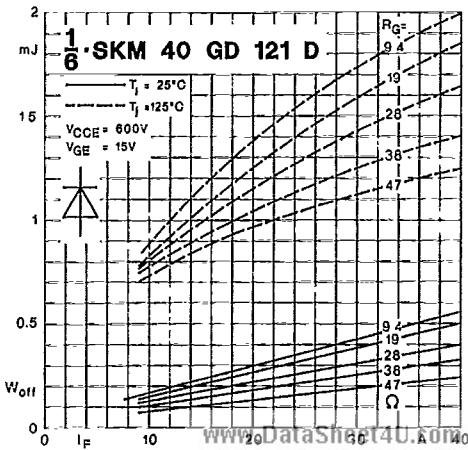


Fig. 42 a Diode turn-off energy dissipation per pulse



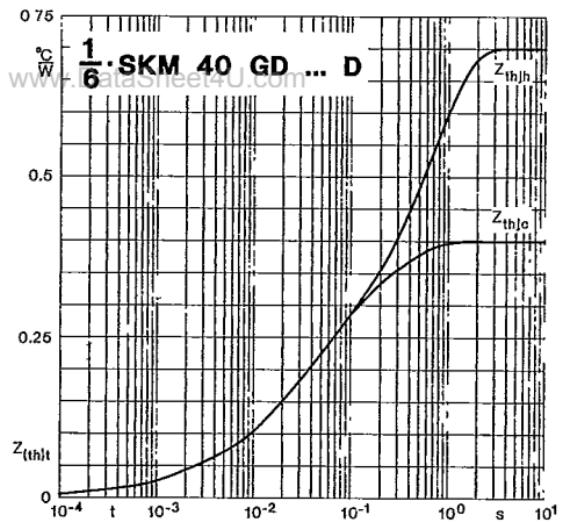


Fig. 51 Transient thermal impedance

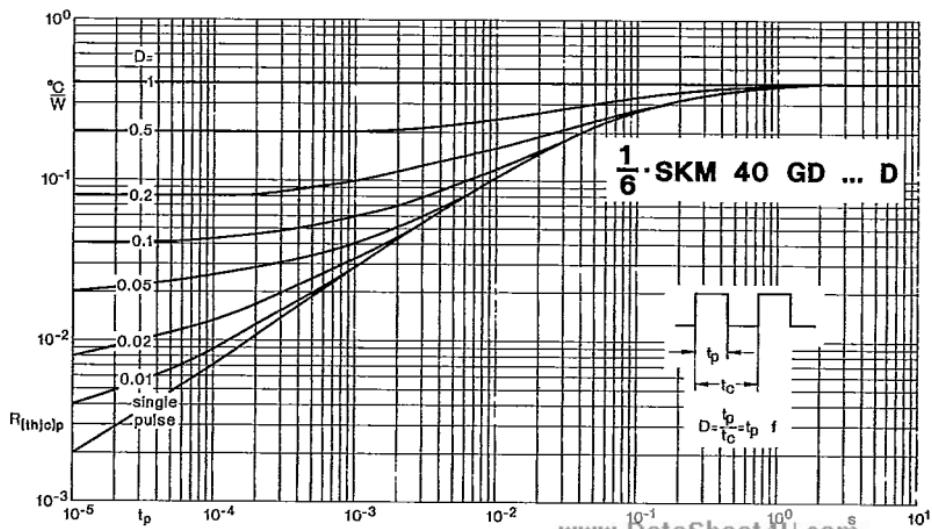
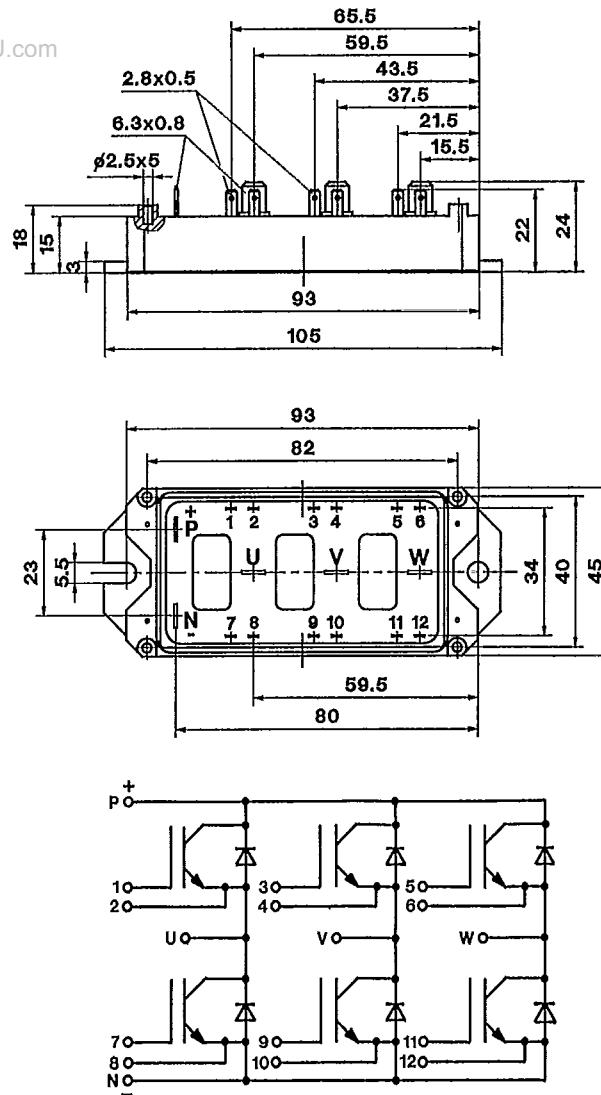


Fig. 52 Thermal impedance under pulse conditions



Dimensions in mm

Mechanical Data		Values	Units	This is an electrostatic discharge sensitive device (ESDS). Please observe the international standard IEC 747-1, Chapter IX.	
Symbol	Conditions	min.	typ.	max.	
M ₁	to heatsink, SI Units	4	—	6	Nm
a	to heatsink, US Units	35	—	53	lb.in.
w		—	—	5x9,81	m/s ²
		—	—	190	g